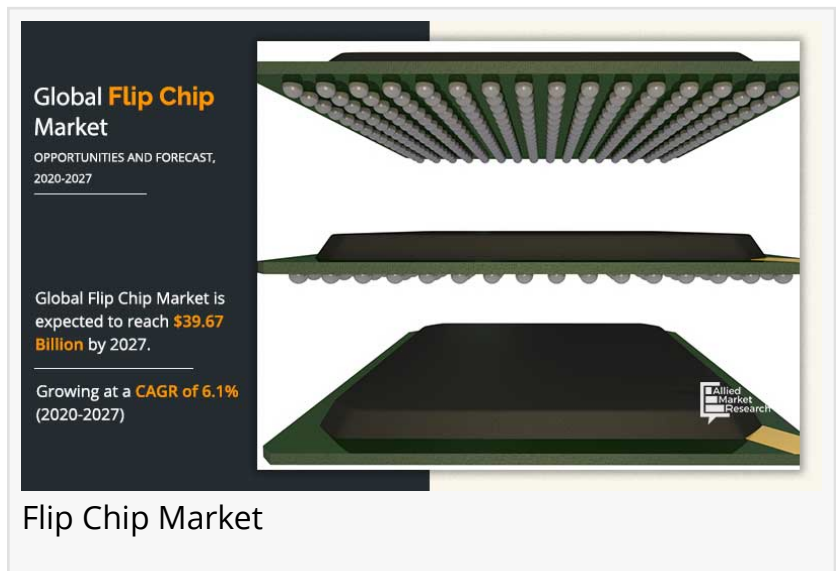


Global Flip Chip Market Projected to Reach \$39.67 Billion by 2027 at a CAGR of 6.1%

PORTLAND, OREGON, UNITED STATES, October 13, 2020 /EINPresswire.com/ -- Surge in demand for smart electronics, sensors, and processors across the globe drives the growth of the global flip chip market. Asia-Pacific contributed the highest share in 2019, and will maintain its dominance throughout the forecast period. Major flip chip manufacturers have halted their assembling activities in European and Asia-Pacific (India, China, and South Korea) regions amid the lockdown during Covid-19 pandemic.



According to the report published by Allied Market Research, the global flip chip market generated \$24.76 billion in 2019, and is estimated to reach \$39.67 billion by 2027, registering a CAGR of 6.1% from 2020 to 2027. The report offers an extensive analysis of changing market dynamics, key winning strategies, business performance, major segments, and competitive scenarios.

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Leading market players analyzed in the research include Advanced Micro Devices, Inc., 3M, Apple Inc., Amkor Technology, Intel Corporation, Fujitsu Limited, Samsung Electronics Co., Ltd., International Business Machines Corporation, Texas Instruments Incorporated, and Taiwan Semiconductor Manufacturing Company Limited.

Covid-19 scenario:

- Major flip chip manufacturers have halted their assembling activities in the European and Asia-Pacific (India, China, and South Korea) regions amid the lockdown during Covid-19 pandemic.

- Frequent lockdown extension amid the spread of Covid-19 across various nations such as India and the U.S. has negatively affected the sale of personal computers, smartphones, and automobiles, which in turn, reduced the demand and production of flip chip.

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The report offers a detailed segmentation of the global flip chip market based on packaging technology, bumping technology, industry, and region.

Based on packaging technology, the 2.5D IC segment contributed to the largest share in 2019, accounting for nearly two-fifths of the total share, and is estimated to maintain its dominant position during the forecast period. However, the 3D IC segment is estimated to portray the highest CAGR of 6.9% during the forecast period.

Based on industry, the electronics segment accounted for the largest share in 2019, holding more than two-fifths of the total share, and is expected to maintain the largest share throughout the forecast period. However, the IT and telecommunication segment is expected to register the highest CAGR of 9.0% from 2020 to 2027.

Based on region, Asia-Pacific contributed the highest share, accounting for more than half of the total market share in 2019, and will maintain its dominance throughout the forecast period. In addition, it is projected to grow at the highest CAGR of 7.0% from 2020 to 2027. The research also analyzes regions including North America, Europe, and LAMEA.

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Key Findings Of The Study

- By packaging technology, the 2.5D IC segment dominated the flip chip market growth. However, the 2D IC segment is expected to exhibit significant growth during the forecast period.

- Depending on bumping technology, the copper pillar segment led the flip chip market share in 2019. However, the gold bumping segment is expected to display highest growth during the forecast period.

- On the basis of industry, the electronics segment witnessed significant growth in the flip chip market trends. However, the IT & telecommunication segment is anticipated to dominate the market during the forecast period in the industry.

- Region wise, Asia-Pacific dominated the flip chip market size in 2019. However, North America is expected to witness significant growth in terms of revenue in the coming years owing to high

demand for smart electronics in this region.

Key Market Segments

By Packaging Technology

- 3D IC
- 2.5D IC
- 2D IC

By Bumping Technology

- Copper Pillar
- Solder Bumping
- Gold Bumping
- Others (Aluminum & Conductive Polymer)

By Industry

- Electronics
- Industrial
- Automotive & Transport
- Healthcare
- IT & Telecommunication
- Aerospace & Defense
- Others

By Region

- North America

- o U.S.
- o Canada

- Europe

- o Germany
- o France
- o UK
- o Rest of Europe

- Asia-Pacific

- oJapan
- oChina
- oIndia
- oRest of Asia-Pacific

- AMEA

- oLatin America
- oMiddle East
- oAfrica

Access Report Summary: <https://www.alliedmarketresearch.com/flip-chip-market>

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[IGCT market is projected to reach \\$17.77 million by 2024](#)

[Chipless RFID Market size is expected to experience considerable growth](#)

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We are in professional corporate relations with various companies and this helps us in digging out market data that helps us generate accurate research data tables and confirms utmost accuracy in our market forecasting. Every data presented in the reports published by us is extracted through primary interviews with top officials from leading companies of domain concerned. Our secondary data procurement methodology includes deep online and offline

research and discussion with knowledgeable professionals and analysts in the industry.

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